

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A metal base circuit board to be used for a hybrid integrated circuit, comprising:

a plurality of circuit pads provided on a metal plate;

[[an]] a first insulating layer in between the plurality of the circuit pads and the metal plate;

a second insulating layer in between the plurality of the circuit pads and the metal plate and underneath the first insulating layer;

a power semiconductor mounted on one circuit pad of the plurality of the circuit pads;

a control semiconductor configured to control the power semiconductor, provided on another circuit pad of the plurality of the circuit pads; and

a low capacitance portion embedded in the metal plate under the first insulating layer, the low capacitance portion embedded in the second insulating layer such that a sidewall of the low capacitance portion is vertically planar with a sidewall of the second insulating layer, and the low capacitance portion disposed under the another circuit pad of the plurality of the circuit pads on which the control semiconductor is mounted.

Claim 2 (Original): The metal base circuit board according to Claim 1, wherein the low capacitance portion is made of a resin containing an inorganic filler and has a dielectric constant of from 2 to 9.

Claim 3 (Previously Presented): The metal base circuit board according to Claim 1, wherein the thickness of the low capacitance portion is from 100 to 1,000 μm .

Claim 4-18 (Canceled).

Claim 19 (New). The metal base circuit board of claim 1, wherein the low capacitance portion is disposed directly under the another circuit pad.